



GaN 50V, 250W,UHF RF Power Transistor

Description

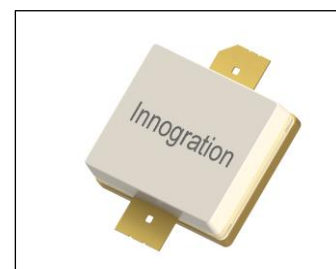
The STBV05250RA2C is a single ended 230 watt capable, GaN HEMT within UHF, ideal for ISM Applications at 433MHz. It can be used in CW, Pulse and any other modulation modes.

There is no guarantee of performance when this part is used in applications designed outside of these frequencies.

- Typical RF performance at selected 433MHz applications with device soldered on heatsink

$V_{DD} = 48V_{dc}$, $V_{GS} = -4.2V$ CW

Freq (MHz)	P1dB (dBm)	P1dB (W)	P1dB Eff (%)	P1dB Gain (dB)	P3dB (dBm)	P3dB (W)	P3dB Eff (%)
435	53.72	235.4	81.6	16.16	54.09	256.7	85.0
438	53.81	240.2	81.8	16.18	54.17	261.5	85.2
445	53.92	246.9	82.0	16.03	54.27	267.5	85.0



Applications

- 433MHz RF Energy
- UHF PA

Important Note: Proper Biasing Sequence for GaN HEMT Transistors

Turning the device ON

1. Set V_{GS} to the pinch-off (V_P) voltage, typically $-5V$
2. Turn on V_{DS} to nominal supply voltage
3. Increase V_{GS} until I_{DS} current is attained
4. Apply RF input power to desired level

Turning the device OFF

1. Turn RF power off
2. Reduce V_{GS} down to V_P , typically $-5V$
3. Reduce V_{DS} down to $0V$
4. Turn off V_{GS}

Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
Drain--Source Voltage	V_{DSS}	+200	Vdc
Gate--Source Voltage	V_{GS}	-8 to +0.5	Vdc
Operating Voltage	V_{DD}	55	Vdc
Maximum gate current	I_{GS}	39.6	mA
Storage Temperature Range	T_{stg}	-65 to +150	°C
Case Operating Temperature	T_C	+150	°C
Operating Junction Temperature	T_J	+225	°C

Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case by FEA $T_C = 85^\circ C$, at $P_d = 50W$	$R_{\theta JC}$	0.85	°C /W



Table 3. Electrical Characteristics (TA = 25°C unless otherwise noted)

DC Characteristics (measured on wafer prior to packaging)

Characteristic	Conditions	Symbol	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	VGS=-8V; IDS=39.6mA	V _{DSS}		200		V
Gate Threshold Voltage	VDS =10V, ID = 39.6mA	V _{GS(th)}	-4	-	-2	V
Gate Quiescent Voltage	VDS =48V, IDS=300mA, Measured in Functional Test	V _{GS(Q)}		-3.2		V

Ruggedness Characteristics

Characteristic	Conditions	Symbol	Min	Typ	Max	Unit
Load mismatch capability	433MHz, Pout=250W pulse CW All phase, No device damages	VSWR		10:1		

TYPICAL CHARACTERISTICS

Figure 1: Efficiency and power gain as function of Pout

**Class C Vds= 48V, Idq=2.3mA
CW Test**

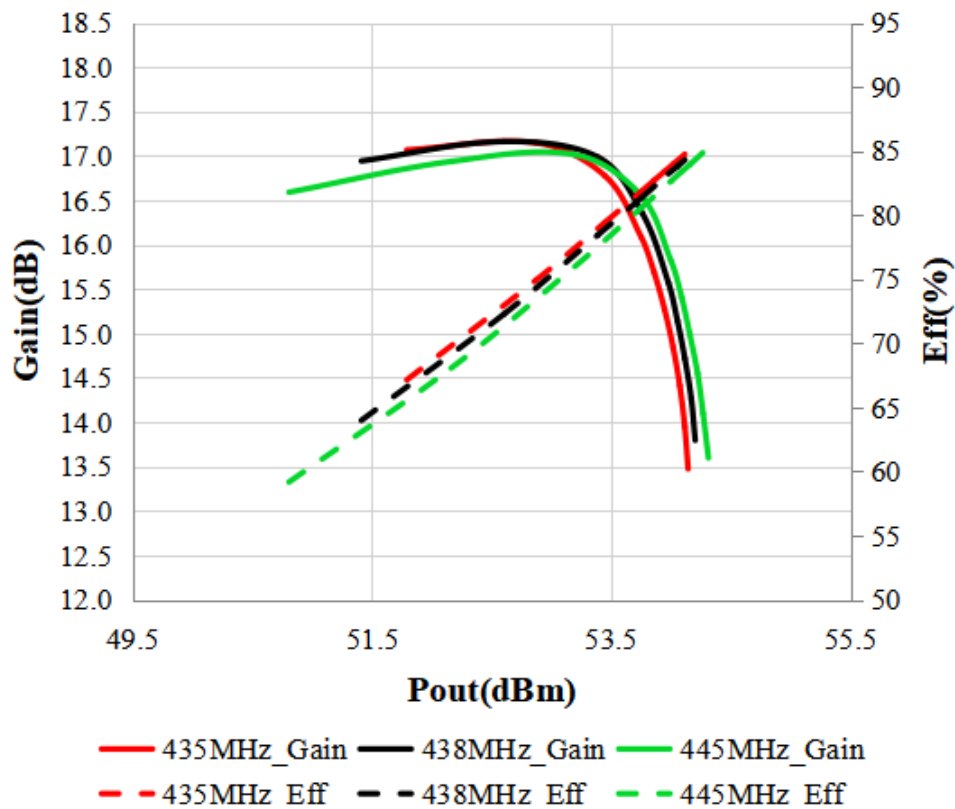


Figure 2: S11/S21 output from Network analyser

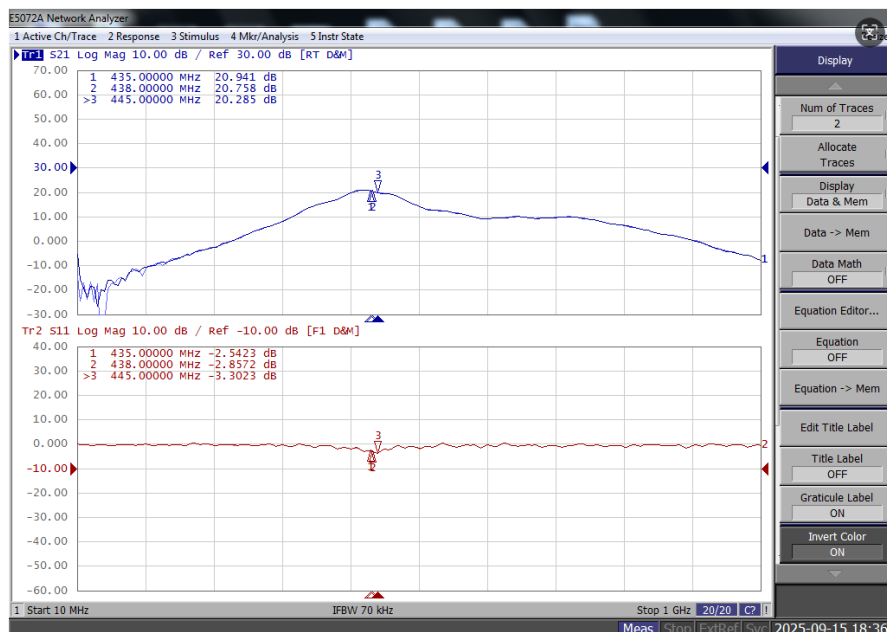
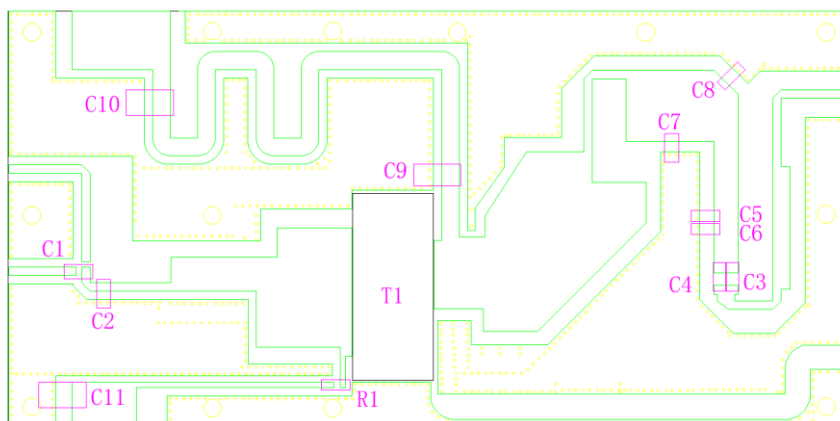
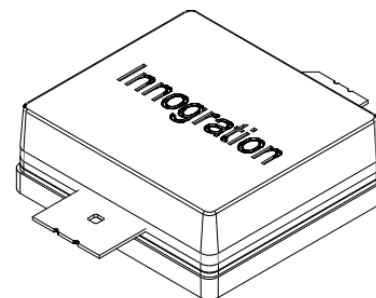
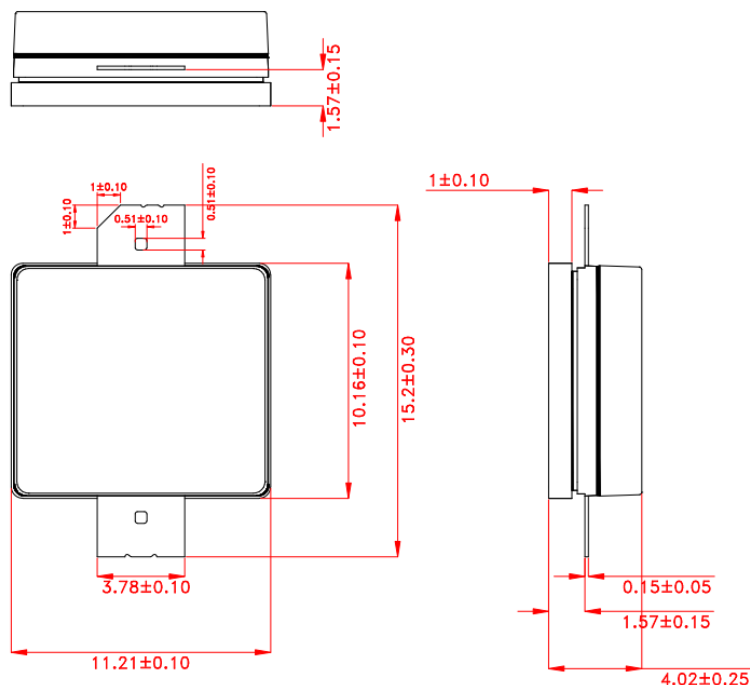


Figure 3: Reference design circuit (RO4350B 30mil, PCB DWG file upon request,)



Part	Quantity	Description	Part Number	Manufacture
C1	1	4.7pF High Q Capacitor	251SHS4R7BSE	TEMEX
C2	1	20pF High Q Capacitor	251SHS200BSE	TEMEX
C3,C4,	2	220pF High Q Capacitor	251SHF221BSE	TEMEX
C5,C6,C7,C8	4	1.0pF High Q Capacitor	251SHS1R0BSE	TEMEX
C9,C10,C11	3	10uF MLCC	GRM32EC72A1 06ME05	Murata
R1	1	10 Ω Power Resistor	ESR03EZPF100	ROHM

Package Dimensions (Unit:mm)



Unit:mm

Tolerance $\pm 0.10\text{mm}$, Except as Noted.

Revision history

Table 1. Document revision history

Date	Revision	Datasheet Status
2024/9/19	Rev 1.0	Preliminary Datasheet

Application data based on LWH—25-38

Disclaimers

Specifications are subject to change without notice. Innogration believes the information contained within this data sheet to be accurate and reliable. However, no responsibility is assumed by Innogration for any infringement of patents or other rights of third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of Innogration. Innogration makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose. "Typical" parameters are the average values expected by Innogration in large quantities and are provided for information purposes only. These values can and do vary in different applications and actual performance can vary over time. All operating parameters should be validated by customer's technical experts for each application. Innogration products are not designed, intended or authorized for use as components in applications intended for surgical implant into the body or to support or sustain life, in applications in which the failure of the Innogration product could result in personal injury or death or in applications for planning, construction, maintenance or direct operation of a nuclear facility. For any concerns or questions related to terms or conditions, pls check with Innogration and authorized distributors

Copyright © by Innogration (Suzhou) Co.,Ltd.